IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Taylor R. Efland Art Unit (parent case): 2815

Serial No.: TBD Examiner (parent case): Clark, Jasmine

Filed: Herewith Docket: TI-30963.1

For: Thermally Enhanced Semiconductor

Chip Having Integrated Bonds Over

Active Circuits

Conf. No.: TBD

PRELIMINARY AMENDMENT

Commissioner For Patents

Alexandria, VA 22313-1450

Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that on or before this date the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA 22313-1450.

Elizabeth Austin

Please enter the following amendment prior to examination of the instant application.

In the Specification:

Please amend the specification by inserting before the first line the sentence:

-- This is a Divisional Application of Serial No. 10/002,022, filed 10/31/2001, which is a non-provisional application claiming priority from provisional application Serial No. 60/246,081, filed 11/03/2000. --